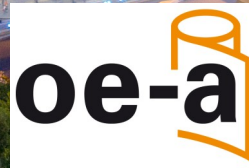




# 3rd IEEE International Flexible Electronics Technology Conference Columbus, Ohio USA (August 8-11, 2021) [ifetc.org](http://ifetc.org)



## Call for Papers Important Dates

Submission deadline: **February 28, 2021**; Notification of acceptance: April 30, 2021  
Final Paper Submission Deadline: May 31, 2021  
Early Bird Registration Deadline: June 30, 2021

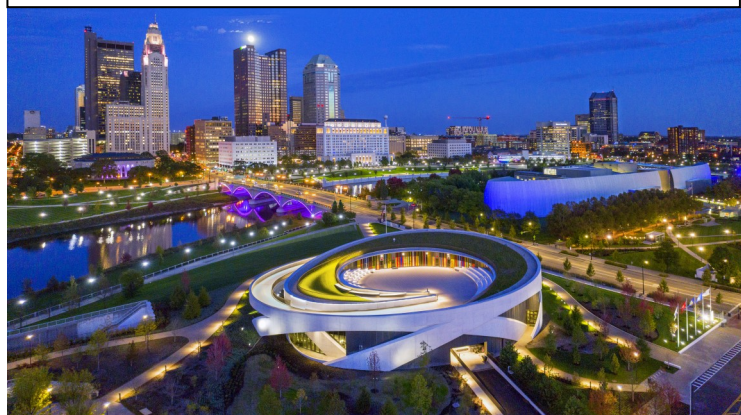
IFETC, started in Ottawa, Canada (2018) is a new EDS-lead international conference, focusing upon printed and flexible hybrid and non-hybrid materials, devices and systems. It will rotate between the Americas, Asia and Europe, heading to Shanghai PRC in 2022. IFETC aims to bring together a wide variety of stakeholders, from chemists, materials scientists, polymer physicists, to mechanical and electrical engineers, the fabrication and manufacturing communities, as well as end-users, e.g. packaging and medical communities. We cordially invite your submissions.

### Logistics:

- ◆ Meeting space at Columbus Convention Center (400 N. High Street)
- ◆ Hotel rooms at [Hilton Columbus Downtown](#) (401 North High) and [Red Roof Plus Hotel](#) (111 East Nationwide)
- ◆ Adjacent Short North, Arena District and North Market

### Important Features:

- ◆ Sunday (Aug. 8): Virtual Short Courses
- ◆ Monday (Aug 9): Plenary talks; Early Evening Mixer and Exhibit Space w/ Grades 8-12 at [CO-SI Science Center](#); IFETC Poster judging session at COSI with awards (1st, 2nd, 3rd)
- ◆ Tuesday (Aug 10): Plenary talks; Open bar, (sponsored by NextFlex) atop architecture award winning [Veteran's Memorial](#) (pictured left); IFETC Banquet in Veteran's Memorial lobby and exhibits
- ◆ Wednesday (Aug 11): Plenary talks; [Women in Engineering](#) Breakfast
- ◆ Manufacturing & Workforce Panel
- ◆ Medical Wearable and Clinical Usage Panel
- ◆ Proceedings in IEEE Xplore; Selected papers in [IEEE J-EDS](#).





All accepted papers presented at the conference will be published in the IFETC2021 proceedings and available on IEEE Xplore. Besides, the authors of selected high quality presented papers will be invited to submit an extended version of the same for consideration of publication in the IEEE Journal of Electron Devices Society (J-EDS). All such submissions must comply with J-EDS author-guidelines and be subjected to the standard IEEE and J-EDS publication policy.



### Full Sponsor



### Technical Co-Sponsors



### Financial Co-Sponsors



### Conference Topics:

- ◆ Materials:
  - Advanced Materials for Active Devices
  - Novel Materials and Stretchable Conductors
  - Low Temperature Processing
- ◆ Devices:
  - Liquid Electronics
  - Flexible IoT Sensors
  - Flexible Bio-medical Sensors
  - Flexible Thin Film Transistors
- ◆ Energy Devices:
  - Flexible Photovoltaics
  - Flexible Energy Harvesting (RF, Heat, Motion, etc.)
  - Flexible Lighting and Displays
  - Flexible Batteries and Supercapacitors
- ◆ RF Components:
  - Flexible RF Components / Connectors, RFID & NFC
  - Flexible Microwave Devices
  - Flexible Antennas
- ◆ Systems:
  - Circuit Design for Flexible Electronics
  - Flexible Printed Electronics
  - Flexible Electronics for Robotics
  - Low Cost Flexible Electronics
  - AI/Machine Learning
- ◆ Bio-Systems:
  - Wearable Devices and Electronic Textiles
  - Human/Machine (Skin/Electronic)
  - Medical School Roundtable
- ◆ Back-End Processing:
  - Microelectronics Integration/Heterogeneous Integration
  - Flexible Hybrid Electronics (FHE) Manufacturing
  - Packaging



## Organizing Committees:

- **General Chair:**
  - ◇ Paul R. Berger, Ohio State & Tampere University
- **Technical Co-Chairs:**
  - ◇ John Anthony, Kentucky
  - ◇ Luisa Petti, Bozen-Bolzano
  - ◇ Giorgio Bazzan, AFRL
- **Financial Chair:**
- **Publication Chair:**
- **Local Arrangements Chair:**
  - ◇ Savas Kaya (Ohio U.)

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- ◇ Paul Blom (MPI-Polymers, Mainz)
- ◇ Jean-Luc Brédas (Arizona)
- ◇ Stephen Forrest (Michigan)
- ◇ Richard Friend (Cambridge)
- ◇ Takao Someya (Tokyo)

## Steering Committee:

- ◆ Ta-Ya Chu (NRC, Canada) - Chair, EDS Flexible Electronics and Displays Committee
- ◆ Xiaojun Guo (Shanghai Jiao Tong University, P.R. China) - IFETC 2022 Program Chair
- ◆ Kazunari Ishimaru (Kioxia, Japan) – Chair, Steering Comm.; EDS VP of Meetings & Conferences
- ◆ Samar K. Saha (Prospicient Devices, USA), EDS Sr. Past President
- ◆ Ravi Todi (Western Digital, USA) - EDS President

## Conference Committee:

- John Anthony (Kentucky) - Organic Synthesis
- Massood Z. Atashbar (Western Michigan) - Flexible Batteries
- C. Daniel Frisbie (Minnesota) - Organic Electronics
- Samson A. Jenekhe (Washington) - Semiconducting Polymers
- Savas Kaya (Ohio Univ.) - Wearable Supercapacitors
- Eric MacDonald (Texas @ El Paso) - Additive Printing
- Matti Mäntysalo (Tampere) - Hybrid Integration
- Luisa Petti (Bozen-Bolzano) - Flexible Devices
- Henning Sirringhaus (Cambridge) - Transport/Devices
- Luisa Torsi (Bari Aldo Moro) - Bioelectronics
- Peide Ye (Purdue) - ALD and advanced processing

## Virtual Short Courses

(Sunday, August 8, 2021):

- Additive Manufacturing
- Automotive
- Healthcare
- Internet of Things
- Smart Buildings
- Smart Packaging

